

Hypersonic

SBS-300+

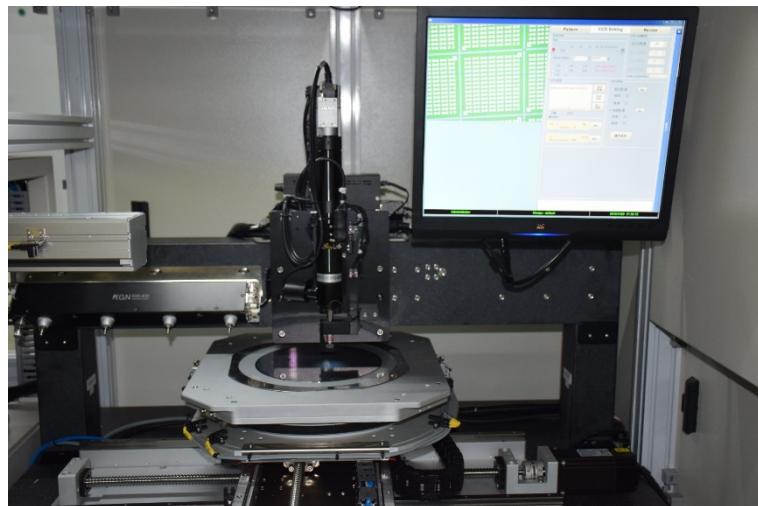
Wafer Inspection System

Features :

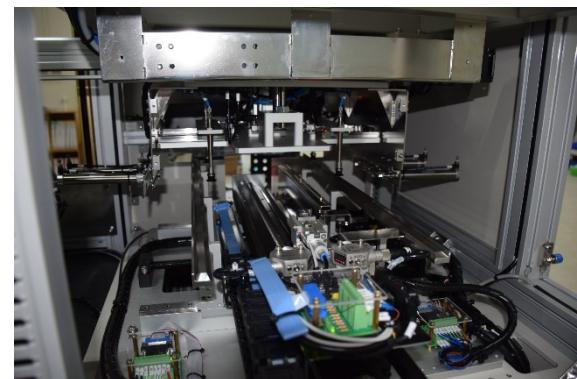
- **Semi-auto Wafer inspection after sawing**
- **Easy to operate by Chinese/English HMI**
- **Auto Load/Unload Port**
- **Auto wafer position alignment**
- **Auto wafer transportation**
- **Auto X-Y stage for wafer inspection**
- **Wafer are selectable in cassette**
- **Sawing Lane running path selected**
- **For both 8" & 12" wafer**
- **High Magnification Camera**



Inspection stage



Transportation



瀚軒股份有限公司

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Hypersonic

SBS-300+

Wafer Inspection System

General specification:

Wafer type

8" & 12" wafer with frame

Wafer Cassette Load/Unload port

8" and 12" wafer cassette

Wafer protection

Work-holder station

Programmable X-Y-θ table

Inspection system

High Magnification Camera module

Operation interface (HMI)

Chinese/English switch

Wafer set up

Joystick function

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